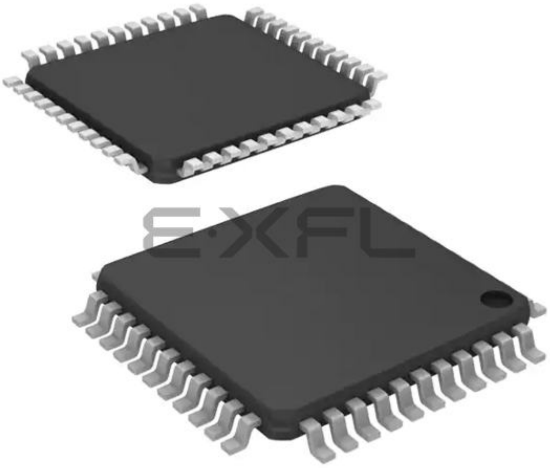
Microchip Technology - DSPIC33EP128GP504-I/PT Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gp504-i-pt

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X PRODUCT FAMILIES

The device names, pin counts, memory sizes and peripheral availability of each device are listed in Table 1 (General Purpose Families) and Table 2 (Motor Control Families). Their pinout diagrams appear on the following pages.

TABLE 1: dsPIC33EPXXXGP50X and PIC24EPXXXGP20X GENERAL PURPOSE FAMILIES

Device	Page Erase Size (Instructions)	Program Flash Memory (Kbytes)	RAM (Kbyte)	Remappable Peripherals							I^2C™	CRC Generator	10-Bit/12-Bit ADC (Channels)	Op Amps/Comparators	CTMU	PTG	I/O Pins	Pins	Packages
				16-Bit/32-Bit Timers	Input Capture	Output Compare	UART	SPI(2)	ECAN™ Technology	External Interrupts(3)									
PIC24EP32GP202	512	32	4	5	4	4	2	2	—	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(4), QFN-S
PIC24EP64GP202	1024	64	8																
PIC24EP128GP202	1024	128	16																
PIC24EP256GP202	1024	256	32																
PIC24EP512GP202	1024	512	48																
PIC24EP32GP203	512	32	4	5	4	4	2	2	—	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
PIC24EP64GP203	1024	64	8																
PIC24EP32GP204	512	32	4	5	4	4	2	2	—	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(4), TQFP, QFN, UQFN
PIC24EP64GP204	1024	64	8																
PIC24EP128GP204	1024	128	16																
PIC24EP256GP204	1024	256	32																
PIC24EP512GP204	1024	512	48																
PIC24EP64GP206	1024	64	8	5	4	4	2	2	—	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
PIC24EP128GP206	1024	128	16																
PIC24EP256GP206	1024	256	32																
PIC24EP512GP206	1024	512	48																
dsPIC33EP32GP502	512	32	4	5	4	4	2	2	1	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(4), QFN-S
dsPIC33EP64GP502	1024	64	8																
dsPIC33EP128GP502	1024	128	16																
dsPIC33EP256GP502	1024	256	32																
dsPIC33EP512GP502	1024	512	48																
dsPIC33EP32GP503	512	32	4	5	4	4	2	2	1	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
dsPIC33EP64GP503	1024	64	8																
dsPIC33EP32GP504	512	32	4	5	4	4	2	2	1	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(4), TQFP, QFN, UQFN
dsPIC33EP64GP504	1024	64	8																
dsPIC33EP128GP504	1024	128	16																
dsPIC33EP256GP504	1024	256	32																
dsPIC33EP512GP504	1024	512	48																
dsPIC33EP64GP506	1024	64	8	5	4	4	2	2	1	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
dsPIC33EP128GP506	1024	128	16																
dsPIC33EP256GP506	1024	256	32																
dsPIC33EP512GP506	1024	512	48																

Note 1: On 28-pin devices, Comparator 4 does not have external connections. Refer to **Section 25.0 “Op Amp/Comparator Module”** for details.
2: Only SPI2 is remappable.
3: INT0 is not remappable.
4: The SSOP and VTLA packages are not available for devices with 512 Kbytes of memory.

TABLE 4-27: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC204/504 AND PIC24EPXXXGP/MC204 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-28: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC206/506 AND PIC24EPXXXGP/MC206 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000
RPOR7	068E	—	—	RP97R<5:0>						—	—	—	—	—	—	—	—	0000
RPOR8	0690	—	—	RP118R<5:0>						—	—	—	—	—	—	—	—	0000
RPOR9	0692	—	—	—	—	—	—	—	—	—	—	RP120R<5:0>						0000

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

FIGURE 4-21: BIT-REVERSED ADDRESSING EXAMPLE

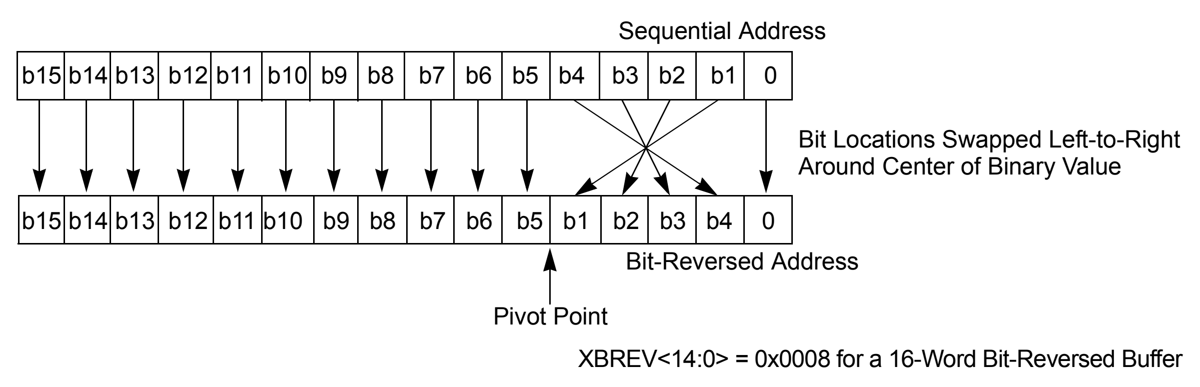


TABLE 4-64: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

REGISTER 8-9: DSADRH: DMA MOST RECENT RAM HIGH ADDRESS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
DSADR<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**Unimplemented:** Read as ‘`0`’
bit 7-0	**DSADR<23:16>:** Most Recent DMA Address Accessed by DMA bits

REGISTER 8-10: DSADRL: DMA MOST RECENT RAM LOW ADDRESS REGISTER

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
DSADR<15:8>							
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
DSADR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**DSADR<15:0>:** Most Recent DMA Address Accessed by DMA bits

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than VDD by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum VIH specification for that particular pin.

See the **"Pin Diagrams"** section for the available 5V tolerant pins and Table 30-11 for the maximum VIH specification for each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a `NOP`, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note: Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0   ; Configure PORTB<15:8>
                   ; as inputs
MOV   W0, TRISB    ; and PORTB<7:0>
                   ; as outputs
NOP                ; Delay 1 cycle
BTSS  PORTB, #13   ; Next Instruction
```

REGISTER 11-26: RPOR8: PERIPHERAL PIN SELECT OUTPUT REGISTER 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP118R<5:0>					
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘0’
bit 13-8	**RP118R<5:0>:** Peripheral Output Function is Assigned to RP118 Output Pin bits (see Table 11-3 for peripheral function numbers)
bit 7-0	**Unimplemented:** Read as ‘0’

REGISTER 11-27: RPOR9: PERIPHERAL PIN SELECT OUTPUT REGISTER 9

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP120R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6	**Unimplemented:** Read as ‘0’
bit 5-0	**RP120R<5:0>:** Peripheral Output Function is Assigned to RP120 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 13-2: TyCON: (TIMER3 AND TIMER5) CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON[1]	—	TSIDL[2]	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0
—	TGATE[1]	TCKPS1[1]	TCKPS0[1]	—	—	TCS[1,3]	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timery On bit[1]

`1` = Starts 16-bit Timery
`0` = Stops 16-bit Timery

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **TSIDL:** Timery Stop in Idle Mode bit[2]

`1` = Discontinues module operation when device enters Idle mode
`0` = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as ‘`0`’

bit 6 **TGATE:** Timery Gated Time Accumulation Enable bit[1]

When TCS = `1`:
This bit is ignored.

When TCS = `0`:
`1` = Gated time accumulation is enabled
`0` = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timery Input Clock Prescale Select bits[1]

`11` = 1:256
`10` = 1:64
`01` = 1:8
`00` = 1:1

bit 3-2 **Unimplemented:** Read as ‘`0`’

bit 1 **TCS:** Timery Clock Source Select bit[1,3]

`1` = External clock is from pin, TyCK (on the rising edge)
`0` = Internal clock (FP)

bit 0 **Unimplemented:** Read as ‘`0`’

Note 1: When 32-bit operation is enabled (T2CON<3> = `1`), these bits have no effect on Timery operation; all timer functions are set through TxCON.

2: When 32-bit timer operation is enabled (T32 = `1`) in the Timerx Control register (TxCON<3>), the TSIDL bit must be cleared to operate the 32-bit timer in Idle mode.

3: The TyCK pin is not available on all timers. See the **“Pin Diagrams”** section for the available pins.

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER(2) (CONTINUED)

bit 1	**SWAP:** SWAP PWMxH and PWMxL Pins bit `1` = PWMxH output signal is connected to PWMxL pins; PWMxL output signal is connected to PWMxH pins `0` = PWMxH and PWMxL pins are mapped to their respective pins
bit 0	**OSYNC:** Output Override Synchronization bit `1` = Output overrides via the OVRDAT<1:0> bits are synchronized to the PWMx period boundary `0` = Output overrides via the OVDDAT<1:0> bits occur on the next CPU clock boundary

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = `1`).

2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a ‘`1`’, the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**PHR:** PWMxH Rising Edge Trigger Enable bit 1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores rising edge of PWMxH
bit 14	**PHF:** PWMxH Falling Edge Trigger Enable bit 1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores falling edge of PWMxH
bit 13	**PLR:** PWMxL Rising Edge Trigger Enable bit 1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores rising edge of PWMxL
bit 12	**PLF:** PWMxL Falling Edge Trigger Enable bit 1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores falling edge of PWMxL
bit 11	**FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit 1 = Leading-Edge Blanking is applied to selected Fault input 0 = Leading-Edge Blanking is not applied to selected Fault input
bit 10	**CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit 1 = Leading-Edge Blanking is applied to selected current-limit input 0 = Leading-Edge Blanking is not applied to selected current-limit input
bit 9-6	**Unimplemented:** Read as ‘0’
bit 5	**BCH:** Blanking in Selected Blanking Signal High Enable bit(1) 1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high 0 = No blanking when selected blanking signal is high
bit 4	**BCL:** Blanking in Selected Blanking Signal Low Enable bit(1) 1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low 0 = No blanking when selected blanking signal is low
bit 3	**BPHH:** Blanking in PWMxH High Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high 0 = No blanking when PWMxH output is high
bit 2	**BPHL:** Blanking in PWMxH Low Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low 0 = No blanking when PWMxH output is low
bit 1	**BPLH:** Blanking in PWMxL High Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high 0 = No blanking when PWMxL output is high
bit 0	**BPLL:** Blanking in PWMxL Low Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low 0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QCAPEN	FLTREN	QFDIV2	QFDIV1	QFDIV0	OUTFNC1	OUTFNC0	SWPAB
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R-x	R-x	R-x	R-x
HOMPOL	IDXPOL	QEBPOL	QEAPOL	HOME	INDEX	QEB	QEA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **QCAPEN:** QEI Position Counter Input Capture Enable bit
1 = Index match event triggers a position capture event
0 = Index match event does not trigger a position capture event

bit 14 **FLTREN:** QEAx/QEBx/INDXx/HOMEx Digital Filter Enable bit
1 = Input pin digital filter is enabled
0 = Input pin digital filter is disabled (bypassed)

bit 13-11 **QFDIV<2:0>:** QEAx/QEBx/INDXx/HOMEx Digital Input Filter Clock Divide Select bits
111 = 1:128 clock divide
110 = 1:64 clock divide
101 = 1:32 clock divide
100 = 1:16 clock divide
011 = 1:8 clock divide
010 = 1:4 clock divide
001 = 1:2 clock divide
000 = 1:1 clock divide

bit 10-9 **OUTFNC<1:0>:** QEI Module Output Function Mode Select bits
11 = The CTNCMPx pin goes high when QEI1LEC ≥ POS1CNT ≥ QEI1GEC
10 = The CTNCMPx pin goes high when POS1CNT ≤ QEI1LEC
01 = The CTNCMPx pin goes high when POS1CNT ≥ QEI1GEC
00 = Output is disabled

bit 8 **SWPAB:** Swap QEA and QEB Inputs bit
1 = QEAx and QEBx are swapped prior to quadrature decoder logic
0 = QEAx and QEBx are not swapped

bit 7 **HOMPOL:** HOMEx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 6 **IDXPOL:** INDXx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 5 **QEBPOL:** QEBx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 4 **QEAPOL:** QEAx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 3 **HOME:** Status of HOMEx Input Pin After Polarity Control
1 = Pin is at logic ‘1’
0 = Pin is at logic ‘0’

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Serial Peripheral Interface (SPI)"** (DS70569) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with Motorola® SPI and SIOP interfaces.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device family offers two SPI modules on a single device. These modules, which are designated as SPI1 and SPI2, are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

> **Note:** In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of the SPI2 module, but results in a lower maximum speed for SPI2. See **Section 30.0 "Electrical Characteristics"** for more information.

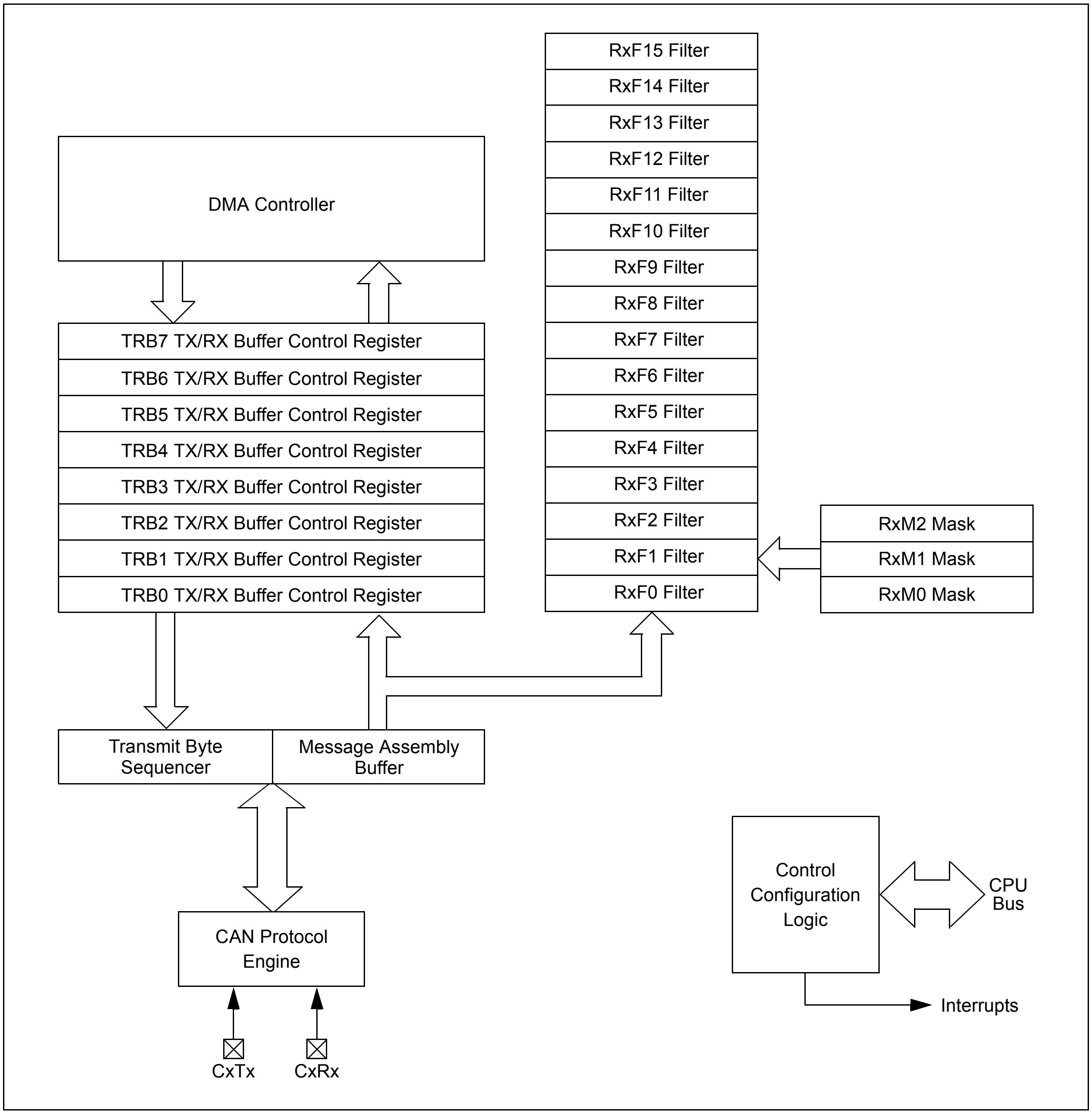
The SPIx serial interface consists of four pins, as follows:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- $\overline{\text{SSx}}$/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, $\overline{\text{SSx}}$ is not used. In 2-pin mode, neither SDOx nor $\overline{\text{SSx}}$ is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

FIGURE 21-1: ECAN™ MODULE BLOCK DIAGRAM



REGISTER 25-7: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

U-0	R/W-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	CVR2OE(1)	—	—	—	VREFSEL	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVR1OE(1)	CVRR	CVRSS(2)	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14 **CVR2OE:** Comparator Voltage Reference 2 Output Enable bit(1)
1 = (AVDD – AVSS)/2 is connected to the CVREF2O pin
0 = (AVDD – AVSS)/2 is disconnected from the CVREF2O pin

bit 13-11 **Unimplemented:** Read as ‘0’

bit 10 **VREFSEL:** Comparator Voltage Reference Select bit
1 = CVREFIN = VREF+
0 = CVREFIN is generated by the resistor network

bit 9-8 **Unimplemented:** Read as ‘0’

bit 7 **CVREN:** Comparator Voltage Reference Enable bit
1 = Comparator voltage reference circuit is powered on
0 = Comparator voltage reference circuit is powered down

bit 6 **CVR1OE:** Comparator Voltage Reference 1 Output Enable bit(1)
1 = Voltage level is output on the CVREF1O pin
0 = Voltage level is disconnected from then CVREF1O pin

bit 5 **CVRR:** Comparator Voltage Reference Range Selection bit
1 = CVRSRC/24 step-size
0 = CVRSRC/32 step-size

bit 4 **CVRSS:** Comparator Voltage Reference Source Selection bit(2)
1 = Comparator voltage reference source, CVRSRC = (VREF+) – (AVSS)
0 = Comparator voltage reference source, CVRSRC = AVDD – AVSS

bit 3-0 **CVR<3:0>** Comparator Voltage Reference Value Selection 0 ≤ CVR<3:0> ≤ 15 bits
When CVRR = 1:
CVREFIN = (CVR<3:0>/24) • (CVRSRC)
When CVRR = 0:
CVREFIN = (CVRSRC/4) + (CVR<3:0>/32) • (CVRSRC)

Note 1: CVRxOE overrides the TRISx and the ANSELx bit settings.
2: In order to operate with CVRSS = 1, at least one of the comparator modules must be enabled.

27.0 SPECIAL FEATURES

> **Note:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

> **Note:** Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '`1111 1111 1111 1111`'. This makes them appear to be `NOP` instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '`1`'s to these locations has no effect on device operation.

> **Note:** Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

Most instructions are a single word. Certain double-word instructions are designed to provide all the required information in these 48 bits. In the second word, the 8 MSbs are '`0`'s. If this second word is executed as an instruction (by itself), it executes as a `NOP`.

The double-word instructions execute in two instruction cycles.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true, or the Program Counter is changed as a result of the instruction, or a PSV or Table Read is performed, or an SFR register is read. In these cases, the execution takes multiple instruction cycles with the additional instruction cycle(s) executed as a `NOP`. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles.

Note: For more details on the instruction set, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).

For more information on instructions that take more than one instruction cycle to execute, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*, particularly the **"Instruction Flow Types"** section.

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "`text`"
(text)	Means "content of `text`"
[text]	Means "the location addressed by `text`"
{ }	Optional field or operation
a ∈ {b, c, d}	a is selected from the set of values b, c, d
<n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write back destination address register ∈ {W13, [W13]+ = 2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSb must be '`0`'
None	Field does not require an entry, can be blank
OA, OB, SA, SB	DSP Status bits: ACCA Overflow, ACCB Overflow, ACCA Saturate, ACCB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}
Wb	Base W register ∈ {W0...W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd--], [++Wd], [--Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd--], [++Wnd], [--Wnd], [Wnd+Wb] }

TABLE 30-12: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	V_{OL}	**Output Low Voltage** 4x Sink Driver Pins[2]	—	—	0.4	V	V_{DD} = 3.3V, I_{OL} ≤ 6 mA, -40°C ≤ T_A ≤ +85°C I_{OL} ≤ 5 mA, +85°C < T_A ≤ +125°C
		Output Low Voltage 8x Sink Driver Pins[3]	—	—	0.4	V	V_{DD} = 3.3V, I_{OL} ≤ 12 mA, -40°C ≤ T_A ≤ +85°C I_{OL} ≤ 8 mA, +85°C < T_A ≤ +125°C
DO20	V_{OH}	**Output High Voltage** 4x Source Driver Pins[2]	2.4	—	—	V	I_{OH} ≥ -10 mA, V_{DD} = 3.3V
		Output High Voltage 8x Source Driver Pins[3]	2.4	—	—	V	I_{OH} ≥ -15 mA, V_{DD} = 3.3V
DO20A	V_{OH1}	**Output High Voltage** 4x Source Driver Pins[2]	1.5[1]	—	—	V	I_{OH} ≥ -14 mA, V_{DD} = 3.3V
			2.0[1]	—	—		I_{OH} ≥ -12 mA, V_{DD} = 3.3V
			3.0[1]	—	—		I_{OH} ≥ -7 mA, V_{DD} = 3.3V
		Output High Voltage 8x Source Driver Pins[3]	1.5[1]	—	—	V	I_{OH} ≥ -22 mA, V_{DD} = 3.3V
			2.0[1]	—	—		I_{OH} ≥ -18 mA, V_{DD} = 3.3V
			3.0[1]	—	—		I_{OH} ≥ -10 mA, V_{DD} = 3.3V

Note 1: Parameters are characterized but not tested.

2: Includes all I/O pins that are not 8x Sink Driver pins (see below).

3: Includes the following pins:
For devices with less than 64 pins: RA3, RA4, RA9, RB<7:15> and RC3
For 64-pin devices: RA4, RA9, RB<7:15>, RC3 and RC15

TABLE 30-13: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[1]** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.[2]**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	V_{BOR}	BOR Event on V_{DD} Transition High-to-Low	2.65	—	2.95	V	V_{DD} **(Notes 2** and **3)**

Note 1: Device is functional at V_{BORMIN} < V_{DD} < V_{DDMIN}, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance.

2: Parameters are for design guidance only and are not tested in manufacturing.

3: The V_{BOR} specification is relative to V_{DD}.

TABLE 30-60: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)**[1] Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	117.6	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period[2]	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	14 TAD		ns	
AD56	FCNV	Throughput Rate	—	—	500	ksps	
AD57a	TSAMP	Sample Time when Sampling any ANx Input	3 TAD	—	—	—	
AD57b	TSAMP	Sample Time when Sampling the Op Amp Outputs (Configuration A and Configuration B)[4,5]	3 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger[2,3]	2 TAD	—	3 TAD	—	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit[2,3]	2 TAD	—	3 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)[2,3]	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On[2,3]	—	—	20	µs	**(Note 6)**

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameters are characterized but not tested in manufacturing.

3: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (AD1CON1<15>) = 1). During this time, the ADC result is indeterminate.

31.2 AC Characteristics and Timing Parameters

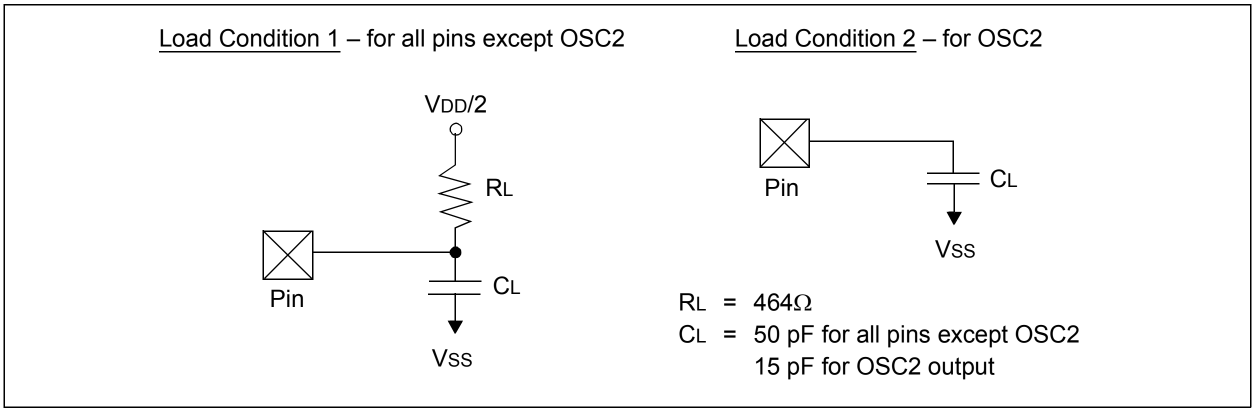
The information contained in this section defines dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X AC characteristics and timing parameters for high-temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 “AC Characteristics and Timing Parameters”**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter OS53 in **Section 30.2 “AC Characteristics and Timing Parameters”** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-9: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



RL = 464Ω
CL = 50 pF for all pins except OSC2
15 pF for OSC2 output

TABLE 31-10: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

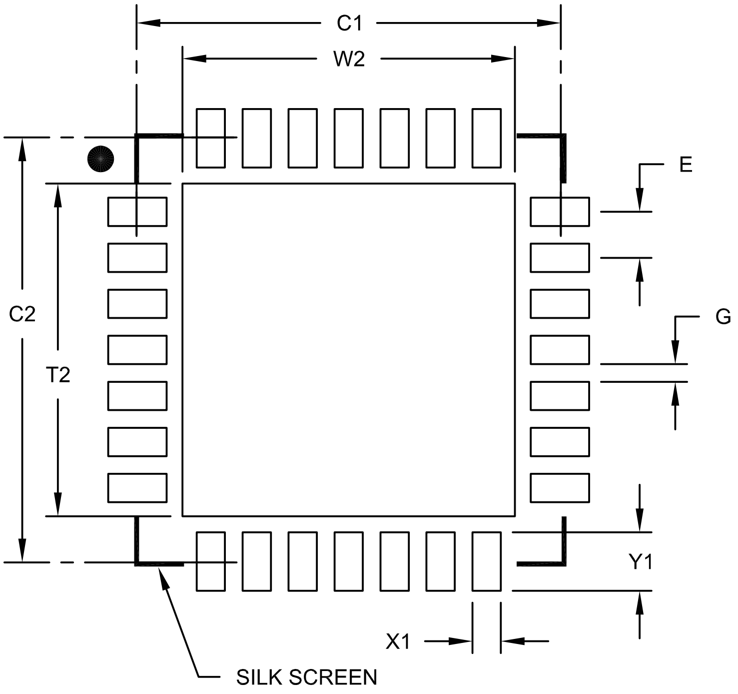
$$\text{Peripheral Clock Jitter} = \frac{D_{CLK}}{\sqrt{\left(\frac{F_{OSC}}{\text{Peripheral Bit Rate Clock}}\right)}}$$

For example: FOSC = 32 MHz, DCLK = 5%, SPIx bit rate clock (i.e., SCKx) is 2 MHz.

$$\text{SPI SCK Jitter} = \left[\frac{D_{CLK}}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}}\right] = \left[\frac{5\%}{\sqrt{16}}\right] = \left[\frac{5\%}{4}\right] = 1.25\%$$

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"	Updated the High-Speed PWM Module Register Interconnection Diagram (see Figure 16-2). Added the TRGCONx and TRIGx registers (see Register 16-12 and Register 16-14, respectively).
Section 21.0 "Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)"	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 22.0 "Charge Time Measurement Unit (CTMU)"	Updated the IRNG<1:0> bit value definitions and added Note 2 in the CTMU Current Control Register (see Register 22-3).
Section 25.0 "Op amp/ Comparator Module"	Updated the Op amp/Comparator I/O Operating Modes Diagram (see Figure 25-1). Updated the User-programmable Blanking Function Block Diagram (see Figure 25-3). Updated the Digital Filter Interconnect Block Diagram (see Figure 25-4). Added **Section 25.1 "Op amp Application Considerations"**. Added Note 2 to the Comparator Control Register (see Register 25-2). Updated the bit definitions in the Comparator Mask Gating Control Register (see Register 25-5).
Section 27.0 "Special Features"	Updated the FICD Configuration Register, updated Note 1, and added Note 3 in the Configuration Byte Register Map (see Table 27-1). Added **Section 27.2 "User ID Words"**.
Section 30.0 "Electrical Characteristics"	Updated the following Absolute Maximum Ratings: • Maximum current out of VSS pin • Maximum current into VDD pin Added Note 1 to the Operating MIPS vs. Voltage (see Table 30-1). Updated all Idle Current (IIDLE) Typical and Maximum DC Characteristics values (see Table 30-7). Updated all Doze Current (IDOZE) Typical and Maximum DC Characteristics values (see Table 30-9). Added Note 2, removed Parameter CM24, updated the Typical values Parameters CM10, CM20, CM21, CM32, CM41, CM44, and CM45, and updated the Minimum values for CM40 and CM41, and the Maximum value for CM40 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Updated Note 2 and the Typical value for Parameter VR310 in the Op amp/ Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Note 1, removed Parameter VRD312, and added Parameter VRD314 to the Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated the Minimum, Typical, and Maximum values for Internal LPRC Accuracy (see Table 30-22). Updated the Minimum, Typical, and Maximum values for Parameter SY37 in the Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Timing Requirements (see Table 30-24). The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-35)